



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Salman Akram

Group Art Unit:

2827

Serial No.:

09/853,111

Examiner:

A. Chambliss

Filed:

May 10, 2001

8888888

§

Atty. Dkt. No.:

MCT.0012D1US

(97-0141)

For:

Method of Fabricating Mounted

Multiple Semiconductor Dies In

A Package (As Amended)

Mail Stop AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

REPLY TO FINAL REJECTION

Sir:

In response to the Final Rejection, please amend the above-referenced patent application as follows:

Date of Deposit: August 7, 2003
I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the Mail Stop **AF**, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450.

Cynthia/L. Hayden